



SPECIFICATION AMENDMENTS

Please amend the paragraph starting on page 7, line 5 accordingly:

The invention also relates ~~also~~ to an apparatus that, on the basis of low contact pressures and slight lateral contacting movements associated with this, permits contact to be made even with small wafer contact areas.

Amend the paragraph starting on page 17, line 23 as follows:

With the foregoing and other objects in view there is provided, in accordance with the invention ~~invention~~¹⁷. A method of testing semiconductor circuits in a test apparatus, which includes the following steps: providing a wafer that has at least one semiconductor integrated circuit with a group of contact areas that define a wafer surface profile; providing a test apparatus that includes a chuck for holding the wafer; providing the test apparatus with a test head that is configured opposite the chuck and that includes a performance board; providing the test apparatus with a probe card that is configured on the test head and that has contacts for making contact with the contact areas of the integrated circuit; providing the contacts with areas that are intended to come into contact with the contact areas of the integrated circuit and that define a test surface

profile; providing the probe card with actuators; using the actuators to align the test surface profile parallel with the wafer surface profile; and using the actuators to enlarge a distance between the performance board and the contacts in a direction substantially orthogonal to the wafer surface profile until the contacts of the probe card have produced an electrical connection with the contact areas of the wafer.

Amend the paragraph starting on page 25, line 11 as follows:

Fig. 4A ~~[[4]]~~ illustrates the inventive method using a simplified embodiment of the test apparatus. The test head 1 has been lowered onto the performance board 3 and has been inserted into the performance board support 16, and contacts 15 produce electrical connection with the tester electronics. Actuators 4 connected to the performance board 3 move the probe card 5 downward.

Amend the paragraph starting on page 25, line 19 as follows:

Fig. 4B ~~[[4A]]~~ shows the initial state of the test apparatus. In this embodiment of the test apparatus, a wafer 12 having contact areas 13 is positioned on a chuck 2 and after the chuck 2 has been extended, the probe card 5 is tilted by the piezoelectric or other actuators 4 until the probe card 5 is parallel to the wafer 12 ~~(See Fig. 4B)~~. Here, the arrows in

the actuators 4 are intended to indicate the different extents of the movement.